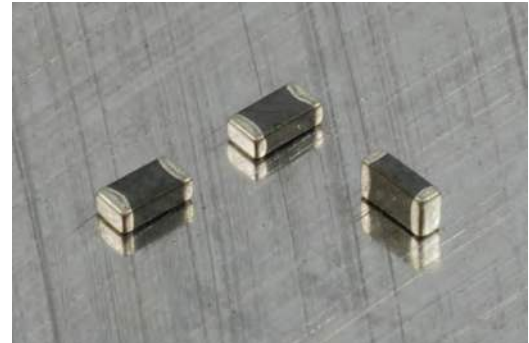
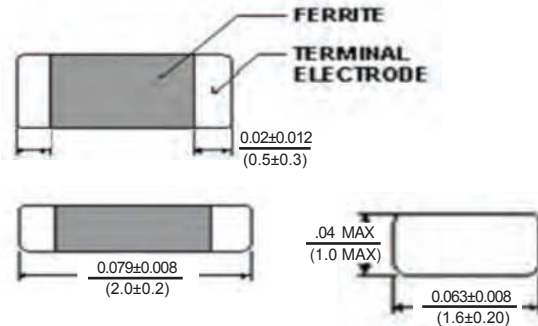




# Multilayer Power Chip Inductor

# MLPC12

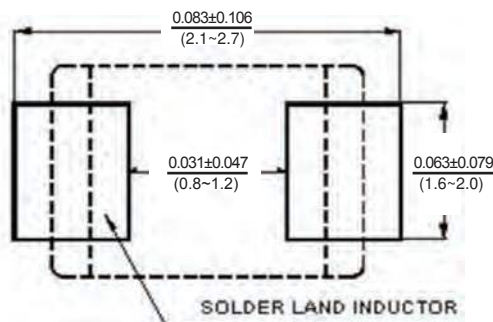
Dimensions:  $\frac{\text{Inches}}{\text{(mm)}}$



Allied Part Number	Inductance (±h)	Tolerance (%)	Test Freq. (MHz)	DCR Max. (Ω)	Rated Current Max. (mA)
MLPC12-R47M-RC	.47	20	3 MHz, 200mV	0.06	1600
MLPC12-R56M-RC	.56	20	3 MHz, 200mV	0.07	1500
MLPC12-1R0M-RC	1.0	20	3 MHz, 200mV	0.09	1300
MLPC12-1R5M-RC	1.5	20	3 MHz, 200mV	0.11	1200
MLPC12-2R2M-RC	2.2	20	3 MHz, 200mV	0.13	1000
MLPC12-3R3M-RC	3.3	20	3 MHz, 200mV	0.17	850
MLPC12-4R7M-RC	4.7	20	3 MHz, 200mV	0.21	800

All specifications subject to change without notice.

## Recommended Pad Layout



## Features

- 0806 EIA Size
- High Current Capacity
- Multilayer Ferrite Construction
- Excellent Solderability Characteristics

## Electrical

**Inductance Range:** .47 $\mu$ h ~ 4.7 $\mu$ h

**Tolerance:** 5% across entire range

Also available in 10% & 20%

**Test Frequency:** 3MHz, 200mV

**Operating Temp:** -55°C ~ 125°C

**Rated Current:** Based on a temp rise of no more than 40°C

## Resistance to Soldering Heat

Pre-heating: 150°C, 1min

Solder Composition: Sn/Ag3.0/Cu0.5

Solder Temperature: 260 ± 5°C

Immersion Time: 10 ± 1sec

No Damage with more than 75% coverage

Inductance within 20 of initial value.

## Test Equipment

(L): HP4291A RF Impedance Analyzer

**DCR:** Chen Hwa 502 BC

**IDC:** HP4284A with HP42841A /

HP4285A with HP42841A

## Physical

**Packaging:** 3000 pieces per 7 inch reel.

**Marking:** None